

ABSTRACT

A wafer cleaning device is disclosed in which a brush is integrally formed with a nozzle for supplying pure water, such that a uniform water screen is formed on a surface of a wafer and particles on the wafer can be entirely removed. The cleaning device includes injectors for ejecting pure water supplied from a pure water supplier onto a wafer; nozzles disposed at one end of each of the injectors; and a brush for cleaning the wafer while moving horizontally between a center and edges of the wafer. The injectors include a first injector for ejecting pure water at an upper position of the wafer toward the center of the wafer, and a second injector disposed adjacent to the brush along one side of a brush arm, the brush arm supporting the brush and moving the brush and second injector toward the wafer.